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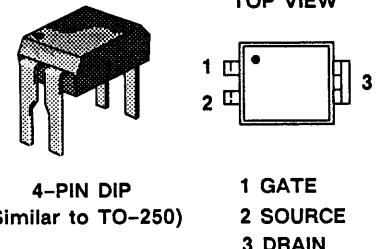
MOSPOWER

IRFD9220, IRFD9223

P-Channel Enhancement Mode Transistors²

PRODUCT SUMMARY

PART NUMBER	V _{(BR)DSS} (VOLTS)	r _{DS(on)} (OHMS)	I _D (AMPS)
IRFD9220	200	1.5	0.60
IRFD9223	150	2.4	0.45



ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

PARAMETERS/TEST CONDITIONS	Symbol	IRFD		Units
		9220	9223	
Drain-Source Voltage	V _{DS}	200	150	V
Gate-Source Voltage	V _{GS}	± 40	± 40	
Continuous Drain Current	T _A = 25°C	I _D	0.60	A
	T _A = 100°C		0.40	
Pulsed Drain Current ¹	I _{DM}	4.8	3.6	A
Avalanche Current (see figure 9)	I _A	0.6	0.45	
Power Dissipation	T _A = 25°C	P _D	1.0	W
	T _A = 100°C		0.4	
Operating Junction & Storage Temperature Range	T _J , T _{stg}	-55 to 150		°C
Lead Temperature (1/16" from case for 10 secs.)	T _L	300		

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	Symbol	Typ.	Max.	Units
Junction-to-Ambient	R _{thJA}	-	120	K/W

¹Pulse width limited by maximum Junction temperature

²Negative signs for current and voltage values have been omitted for the sake of clarity

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

P-Channel Device
 Negative signs have been omitted for clarity

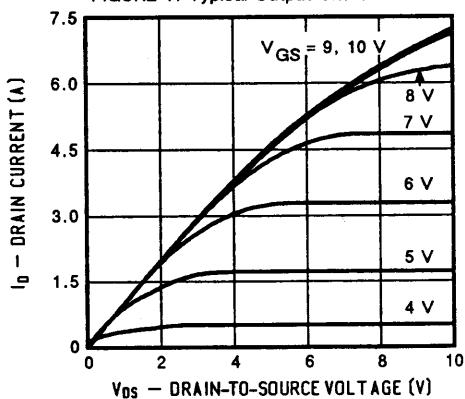
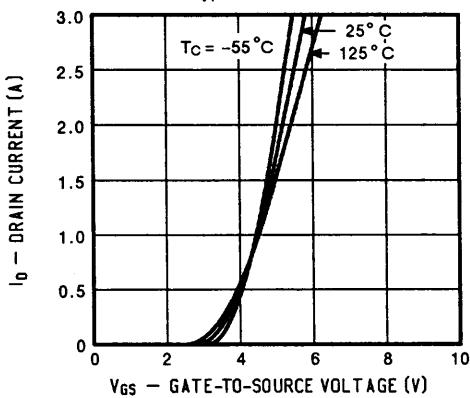
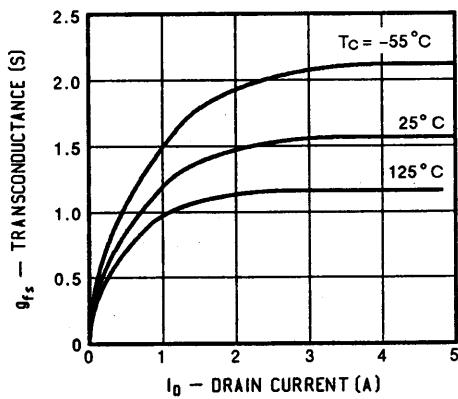
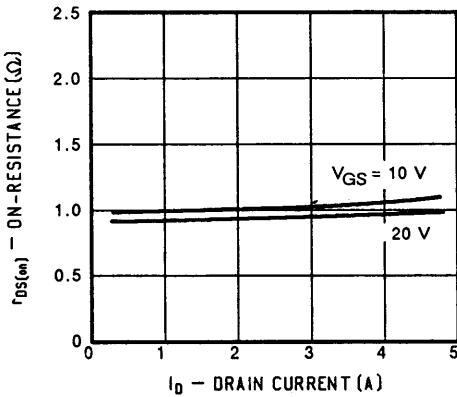
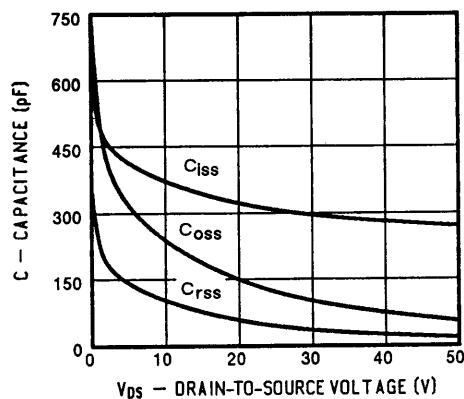
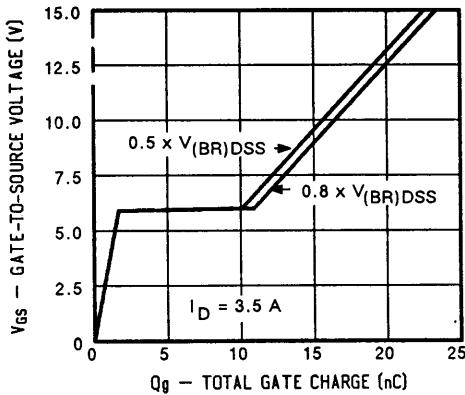
PARAMETERS/TEST CONDITIONS		Symbol	Min.	Typ.	Max.	Units
Drain-Source Breakdown Voltage $V_{GS} = 0$, $I_D = 250 \mu\text{A}$	IRFD9220 IRFD9223	$V_{(\text{BR})\text{DSS}}$	200 150	- -	- -	V
Gate Threshold Voltage $V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$		$V_{GS(\text{th})}$	2.0	-	4.0	
Gate-Body Leakage $V_{DS} = 0$, $V_{GS} = \pm 20 \text{ V}$		I_{GSS}	-	-	100	nA
Zero Gate Voltage Drain Current $V_{DS} = V_{(\text{BR})\text{DSS}}$, $V_{GS} = 0$		I_{DSS}	-	-	250	μA
Zero Gate Voltage Drain Current $V_{DS} = 0.8 \times V_{(\text{BR})\text{DSS}}$, $V_{GS} = 0$, $T_J = 125^\circ\text{C}$		I_{DSS}	-	-	1000	
On-State Drain Current ² $V_{DS} = 5.0 \text{ V}$, $V_{GS} = 10 \text{ V}$	IRFD9220 IRFD9223	$I_{D(\text{on})}$	0.60 0.45	- -	- -	A
Drain-Source On-State Resistance ² $V_{GS} = 10 \text{ V}$, $I_D = 0.30 \text{ A}$	IRFD9220 IRFD9223	$r_{DS(\text{on})}$	-	1.0 2.0	1.5 2.4	Ω
Drain-Source On-State Resistance ² $V_{GS} = 10 \text{ V}$, $I_D = 0.30 \text{ A}$, $T_J = 125^\circ\text{C}$	IRFD9220 IRFD9223	$r_{DS(\text{on})}$	-	2.2 3.5	2.7 4.3	
Forward Transconductance ² $V_{DS} = 15 \text{ V}$, $I_D = 1.5 \text{ A}$		g_{fs}	1.0	1.4	-	$S(\text{U})$
Input Capacitance	$V_{GS} = 0$ $V_{DS} = 25 \text{ V}$ $f = 1 \text{ MHz}$	C_{iss}	-	310	400	pF
Output Capacitance		C_{oss}	-	110	125	
Reverse Transfer Capacitance		C_{rss}	-	40	45	
Total Gate Charge	$V_{DS} = 0.8 \times V_{(\text{BR})\text{DSS}}$, $V_{GS} = 10 \text{ V}$, $I_D = 3.6 \text{ A}$ (Gate charge is essentially independent of operating temperature)	Q_g	-	16	22	nC
Gate-Source Charge		Q_{gs}	-	1.0	-	
Gate-Drain Charge		Q_{gd}	-	8.6	-	
Turn-On Delay Time	$V_{DD} = 100 \text{ V}$, $R_L = 333 \Omega$ $I_D = 0.3 \text{ A}$, $V_{GEN} = 10 \text{ V}$ $R_G = 25 \Omega$ (Switching time is essentially independent of operating temperature)	$t_{d(\text{on})}$	-	10	40	ns
Rise Time		t_r	-	23	50	
Turn-Off Delay Time		$t_{d(\text{off})}$	-	45	50	
Fall Time		t_f	-	31	40	

SOURCE-DRAIN DIODE RATINGS & CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

PARAMETERS/TEST CONDITIONS		Symbol	Min.	Typ.	Max.	Units
Continuous Current	IRFD9220 IRFD9223	I_S	-	-	0.60 0.45	A
Pulsed Current ¹	IRFD9220 IRFD9223	I_{SM}	-	-	4.8 3.6	
Forward Voltage ² $I_F = I_S$, $V_{GS} = 0$	IRFD9220 IRFD9223	V_{SD}	-	-	4.0 3.5	V
Reverse Recovery Time $I_F = I_S$, $dI_F/dt = 100 \text{ A}/\mu\text{s}$		t_{rr}	-	105	-	ns
Reverse Recovered Charge $I_F = I_S$, $dI_F/dt = 100 \text{ A}/\mu\text{s}$		Q_{rr}	-	0.23	-	μC

¹ Pulse width limited by maximum junction temperature

² Pulse test: Pulse width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$

PERFORMANCE CURVES (25°C Unless otherwise noted)
FIGURE 1: Typical Output Characteristics

FIGURE 2: Typical Transfer Characteristics

FIGURE 3: Typical Transconductance

FIGURE 4: Typical On-Resistance

FIGURE 5: Typical Capacitance

FIGURE 6: Typical Gate Charge


PERFORMANCE CURVES (25°C Unless otherwise noted)

FIGURE 7: On-Resistance vs. Junction Temperature

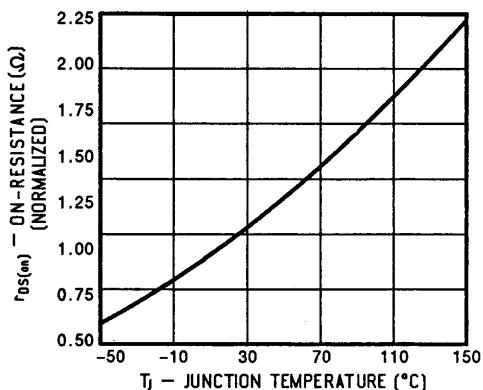


FIGURE 8: Typical Source-Drain Diode Forward Voltage

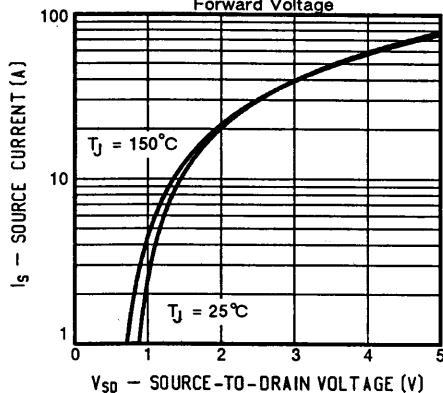


FIGURE 9: Maximum Avalanche and Drain Current vs. Ambient Temperature

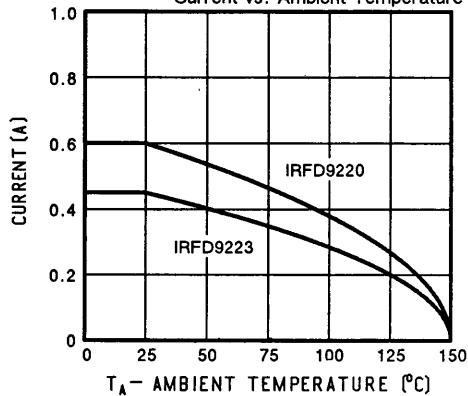
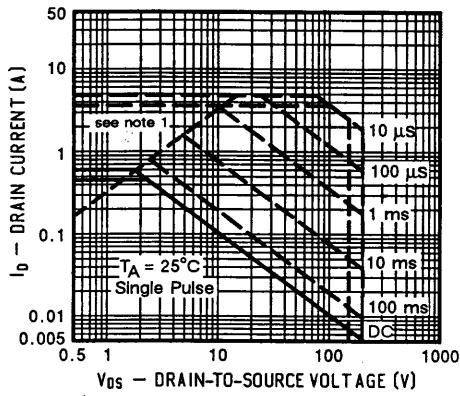


FIGURE 10: Safe Operating Area



¹Operation in this area may be limited by $r_{DS(on)}$